

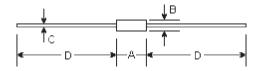
SILICON EPITAXIAL PLANAR DIODE

Features

Silicon Epitaxial Planar Diodes fast switching diode.

This diode is also available in MiniMELF case with the type designation LL4148.

DO-35



| DIMENSIONS | | | | | | | | | |
|------------|--------|-------|-------|------|------|--|--|--|--|
| DIM | inches | | mm | | Note | | | | |
| | Min. | Max. | Min. | Max. | Note | | | | |
| Α | - | 0.154 | 1 | 3.9 | | | | | |
| В | - | 0.075 | 1 | 1.9 | ф | | | | |
| С | - | 0.020 | - | 0.52 | ф | | | | |
| D | 1.083 | - | 27.50 | - | | | | | |

Absolute Maximum Ratings (T_a=25°C)

| | Symbols | Values | Units |
|---|-----------------------|-------------------|--------------|
| Reverse Voltage | V _R | 75 | Volts |
| Peak reverse voltage | V _{RM} | 100 | Volts |
| Rectified current (Average) Half wave rectification with Resist. Load at T _{amb} =25 °C and f≥50Hz | l _o 150 ¹) | | mA |
| Surge forward current at t<1s and $T_j \! = \! 25^{\circ}\!\mathrm{C}$ | I _{FSM} | 500 | mA |
| Power dissipation at $\rm T_{amb} = 25^{\circ}\rm C$ | P _{tot} | 500 ¹⁾ | mW |
| tion Temperature T _j 200 | | 200 | $^{\circ}$ C |
| Storage temperature range | T _s | -65 to +200 | $^{\circ}$ |

Note:

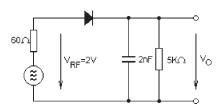
⁽¹⁾ Valid provided that leads at a distance of 8 mm from case are kept at ambient temperature

Characteristics at T₁=25℃

| | Symbols | Min. | Тур. | Max. | Units |
|--|--|-------------|-------------|---------------|----------------|
| Forward voltage at I _F =10mA | V _F | - | - | 1 | Volt |
| Leakage current at V,=20V at V,=75V at V,=20V, T,=150°C | I _R I _R I _R | - - - | - - - | 25 5 50 | nA uA uA |
| Reverse breakdown voltage tested wiht 100uA pulses | V _{(BR)R} | 100 | - | - | Volts |
| Capacitance at $V_r = V_R = 0$ | C _{tot} | - | - | 4 | ρF |
| Voltage rise when switching ON tested with 50mA forward pulses t_p =0.1uS, rise time<30nS, t_p =5 to 100KHz | V _{fr} | - | - | 2.5 | Volts |
| Reverse recovery time from I $_{\rm F}$ =10mA to I $_{\rm R}$ =1mA, V $_{\rm R}$ =6V, R $_{\rm L}$ =100 Ω | t _{rr} | - | - | 4 | nS |
| Thermal resistance junction to ambient Air | R _{thA} | - | - | 0.35 1) | K/mW |
| Rectification efficiency at f=100MHz, V _{RF} =2V | η _ν | 0.45 | - | - | - |

Note:

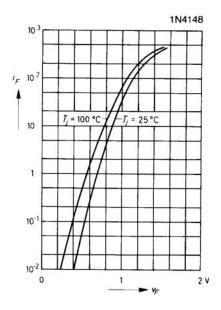
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Rectification efficiency measurement circuit

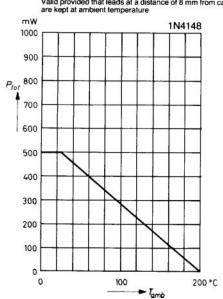
RATINGS AND CHARACTERISTIC CURVES

Forward characteristics

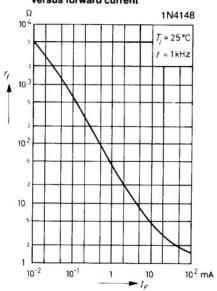


Admissible power dissipation versus ambient temperature

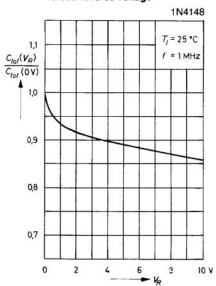
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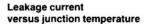
Dynamic forward resistance versus forward current

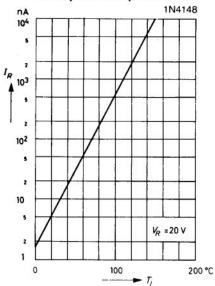


Relative capacitance versus reverse voltage



RATINGS AND CHARACTERISTIC CURVES





Admissible repetitive peak forward current versus pulse duration

Valid provided that leads at a distance of 8 mm from case are kept at ambient temperature

